

**WF6033**
*Water Soluble Liquid Flux*

**Product Description**

WF6033, Asahi's water soluble liquid flux exhibits fluxing ability that shows excellent capillary action on plated through-holes and also reducing solder bridging. The neutral chemistry of this flux is neither acidic nor alkaline. This is an important factor related directly to the reliability and high speed soldering and cleaning of printed circuit assemblies. This flux does not attack properly cured solder masks or FR-4 epoxy glass laminate.

**Application**

WF6033 is specially formulated for spraying, foaming and dipping process. Recommended on-board preheat temperature is about 80 - 90°C. This flux is compatible with both SnPb and lead free solders.

**Residue Removal**

Flux residue can be removed by plain water at 60 +/- 5 °C. Washing of the PCB when soldered with WF6033 should be done within 4 hours time length.

**Recommended Solvent**

Asahi's complementary Solvent #3000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

**Health and Safety**

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

**Storage**

Under proper storage condition, WF6033 can be stored for up to 6 months. WF6033 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

**Packaging**

Available in 20kg/carboy.

**Specification**

Item	Result
State	Liquid
Colour	Pale yellow
Specific Gravity @ 25°C	0.860 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 3hr)	20.5 +/- 2.0 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	2.0 +/- 0.2 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	46 +/- 4 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
IPC-TM-650 2.6.3.3	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "H", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ORH1
IPC J-STD-004	
pH	6.5 +/- 1
Flash Point	16°C
Spread Factor	> 80% (SnPb)
JIS Z 3197 8.3.1.1	

**DISCLAIMER OF LIABILITY**

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